

# Panasonic

MOS FET  
FCAB21520L1

## FCAB21520L1

Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

### ■ Features

- Source-source ON resistance: RSS(on) typ. = 1.6 mΩ (VGS = 3.8 V)
- CSP(Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL : Level 1)

### ■ Marking Symbol: 7T

### ■ Packaging

Embossed type (Thermo-compression sealing) : 1 000 pcs / reel (standard)

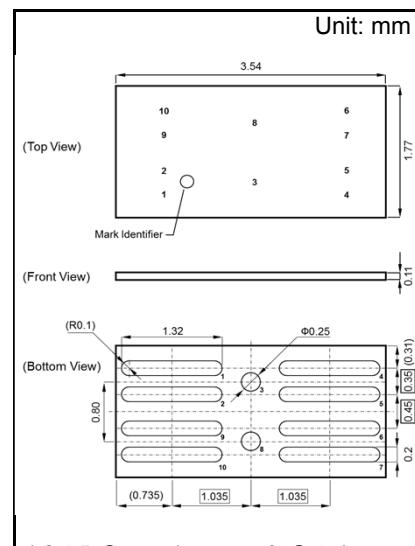
### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	±8	V
Source Current	DC <sup>*1</sup>	IS1	A
	DC <sup>*2</sup>	IS2	A
	Pulse <sup>*3</sup>	ISp	A
Total Power Dissipation	DC <sup>*1</sup>	PD1	W
	DC <sup>*2</sup>	PD2	W
Channel Temperature	Tch	150	°C
Storage Temperature Range	Tstg	-55 to +150	°C
Thermal Resistance (ch-a)	Rth <sup>*1</sup>	232	°C/W
	Rth <sup>*2</sup>	33	°C/W

Note <sup>\*1</sup> Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm )  
using the minimum recommended pad size (36 µm Copper ).

<sup>\*2</sup> Mounted on Ceramic substrate (70 mm × 70 mm × t1.0 mm).

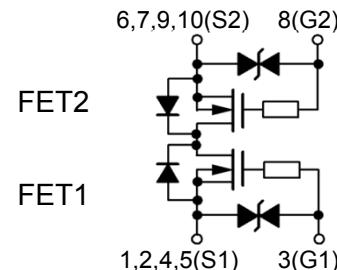
<sup>\*3</sup> t = 10 µs, Duty Cycle ≤ 1 %



1,2,4,5. Source1(FET1) 3. Gate1 (FET1)  
6,7,9,10. Source2(FET2) 8. Gate2 (FET2)

Panasonic	TCSP1835011-N2
JEITA	—
Code	—

### Equivalent Circuit



■ Electrical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ 

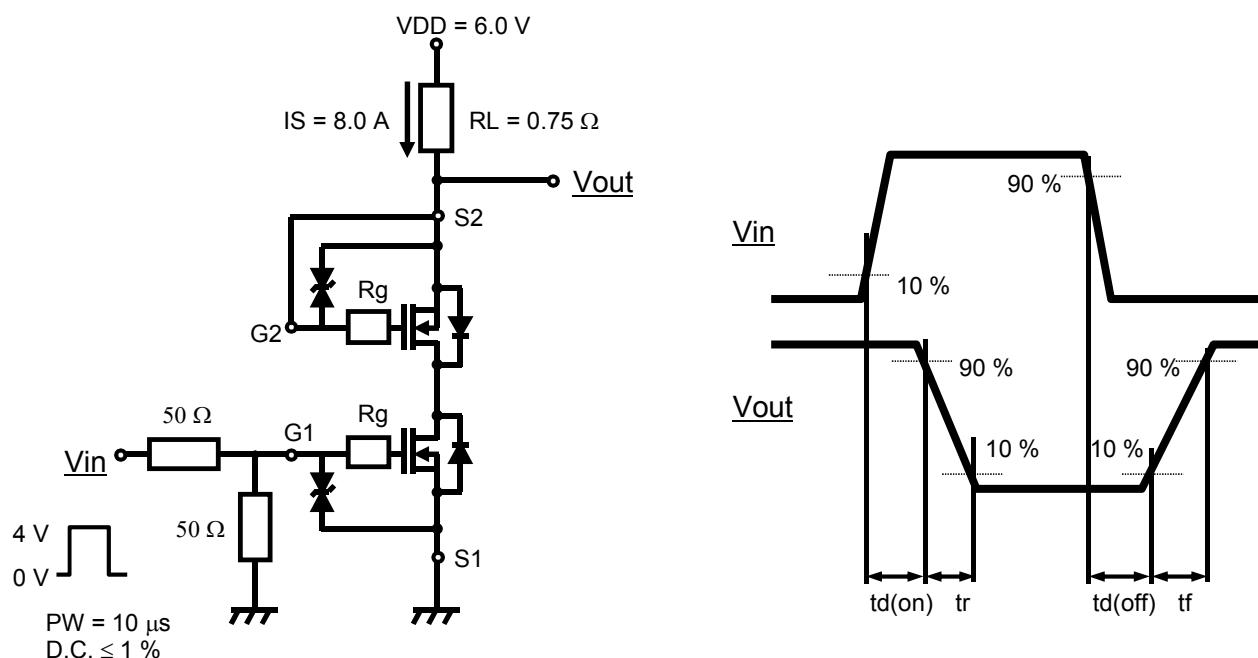
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	V <sub>SSS</sub>	IS = 1.0 mA, V <sub>GS</sub> = 0 V	12			V
Zero Gate Voltage Source Current	I <sub>SSS</sub>	V <sub>SS</sub> = 12 V, V <sub>GS</sub> = 0 V			1.0	$\mu\text{A}$
Gate-source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = $\pm 8$ V, V <sub>SS</sub> = 0 V			$\pm 10$	$\mu\text{A}$
		V <sub>GS</sub> = $\pm 5$ V, V <sub>SS</sub> = 0 V			$\pm 1.0$	
Gate-source Threshold Voltage	V <sub>th</sub>	IS = 1.64 mA, V <sub>SS</sub> = 10 V	0.35	0.90	1.40	V
Source-source On-state Resistance	R <sub>S(on)1</sub>	IS = 8.0 A, V <sub>GS</sub> = 4.5 V	1.1	1.45	2.0	$\text{m}\Omega$
	R <sub>S(on)2</sub>	IS = 8.0 A, V <sub>GS</sub> = 3.8 V	1.15	1.6	2.1	
	R <sub>S(on)3</sub>	IS = 8.0 A, V <sub>GS</sub> = 3.1 V	1.2	1.8	3.0	
	R <sub>S(on)4</sub>	IS = 8.0 A, V <sub>GS</sub> = 2.5 V	1.4	2.3	4.5	
Body Diode Forward Voltage	V <sub>F(s-s)</sub>	IF = 8.0 A, V <sub>GS</sub> = 0 V		0.7	1.2	V
Input Capacitance <sup>1</sup>	C <sub>iss</sub>			5250		pF
Output Capacitance <sup>1</sup>	C <sub>oss</sub>	V <sub>SS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 kHz		700		
Reverse Transfer Capacitance <sup>1</sup>	C <sub>rss</sub>			630		
Turn-on Delay Time <sup>1,2</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 6.0 V, V <sub>GS</sub> = 0 to 4.0 V IS = 8.0 A		1.5		$\mu\text{s}$
Rise Time <sup>1,2</sup>	t <sub>r</sub>			2.6		
Turn-off Delay Time <sup>1,2</sup>	t <sub>d(off)</sub>	V <sub>DD</sub> = 6.0 V, V <sub>GS</sub> = 4.0 to 0 V IS = 8.0 A		6.8		$\mu\text{s}$
Fall Time <sup>1,2</sup>	t <sub>f</sub>			4.1		
Total Gate Charge <sup>1</sup>	Q <sub>g</sub>	V <sub>DD</sub> = 6.0 V V <sub>GS</sub> = 0 to 4.0 V IS = 8.0 A		38		nC
Gate-source Charge <sup>1</sup>	Q <sub>gs</sub>			20		
Gate-drain Charge <sup>1</sup>	Q <sub>gd</sub>			10		

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Guaranteed by design, not subject to production testing

\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

Note2:Measurement circuit

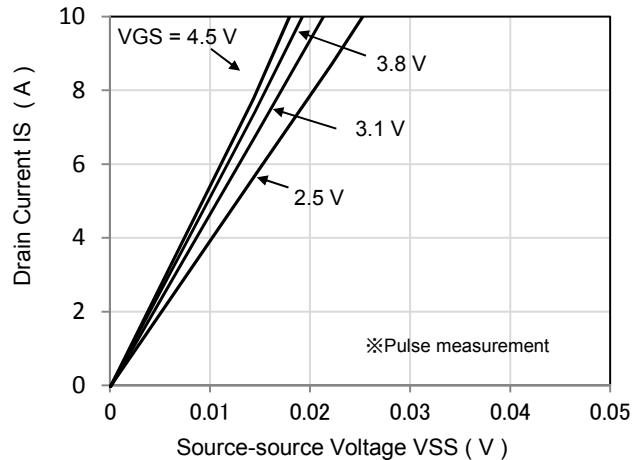


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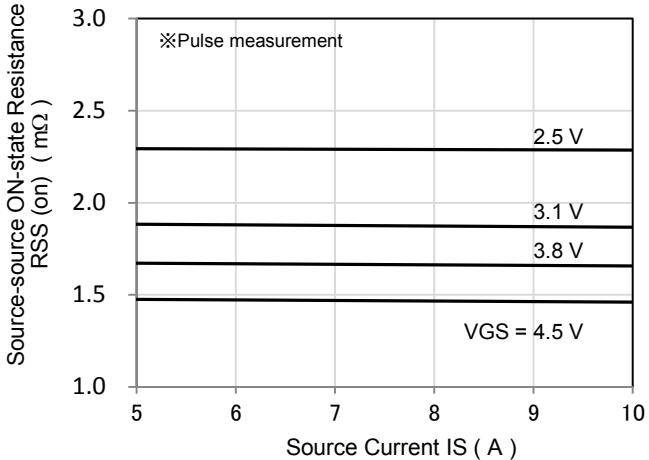
MOS FET

**FCAB21520L1**Technical Data ( reference )

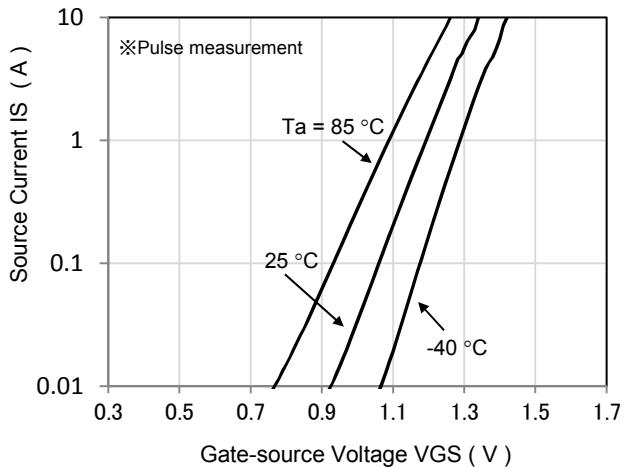
IS - VSS



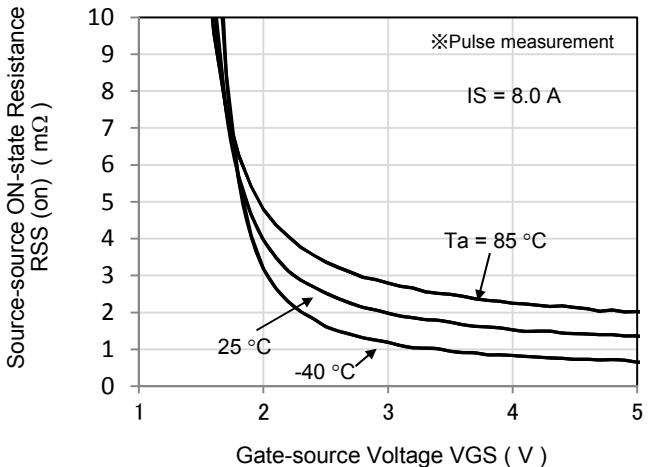
RSS(on) - IS



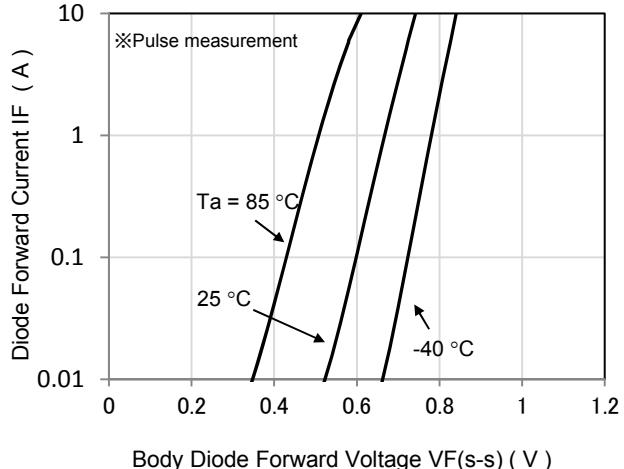
IS - VGS



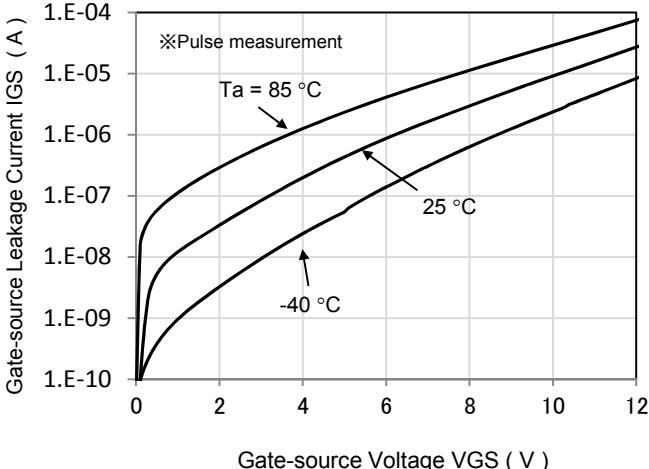
RSS(on) - VGS

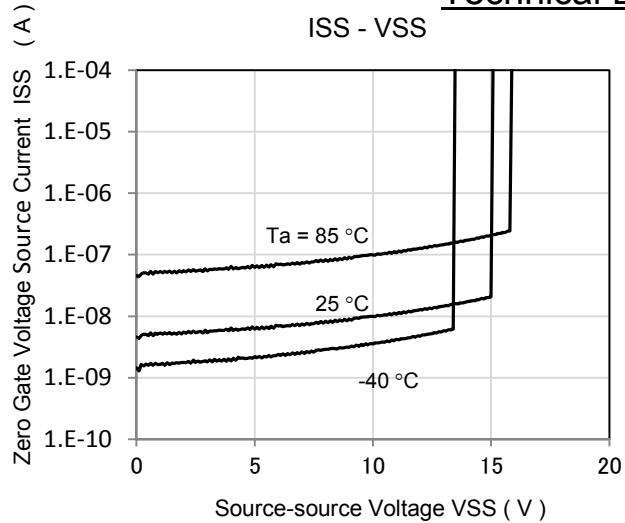


IF - VF(s-s)

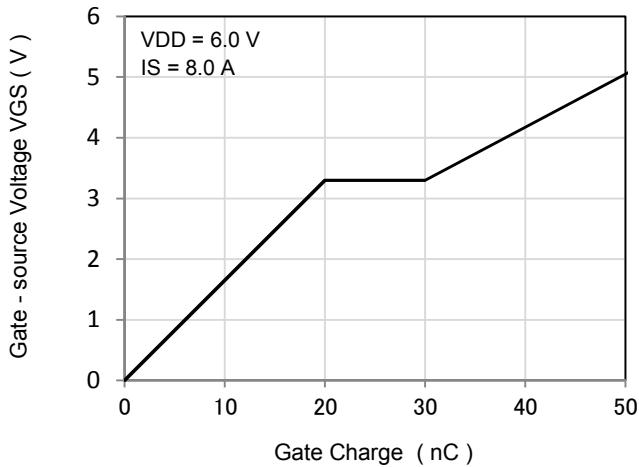
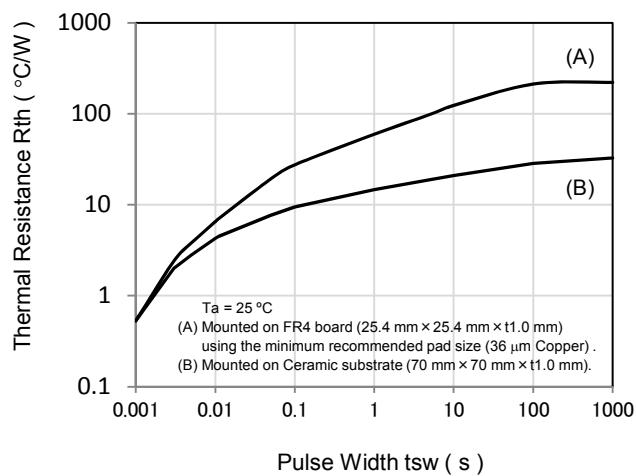
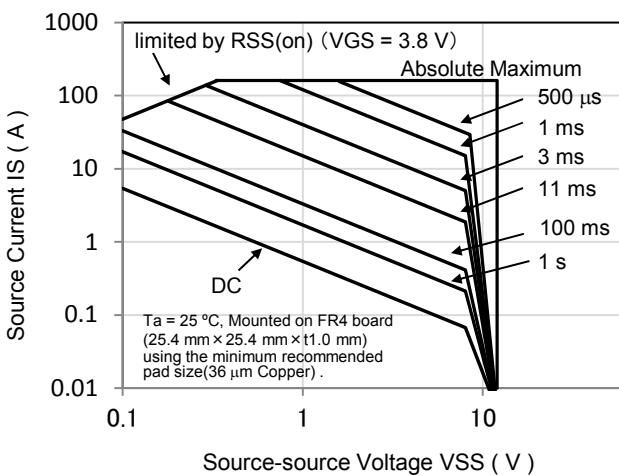
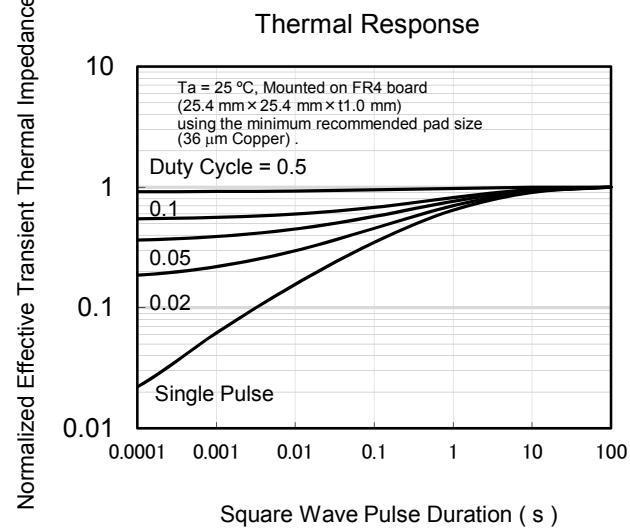


IGS - VGS



Technical Data ( reference )

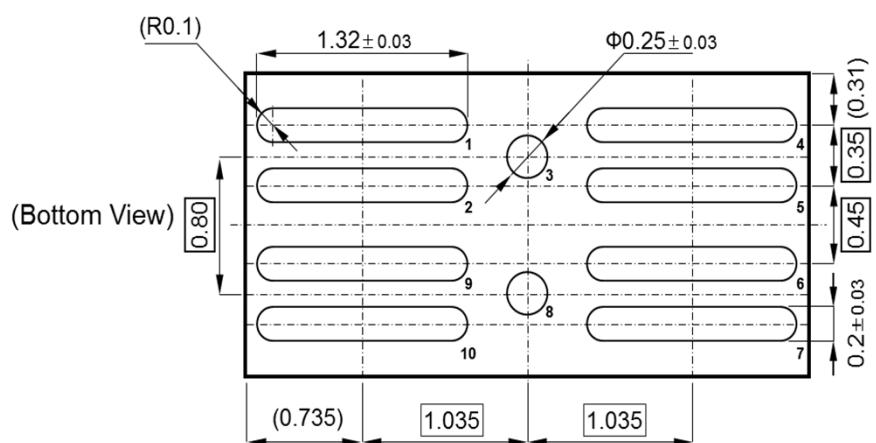
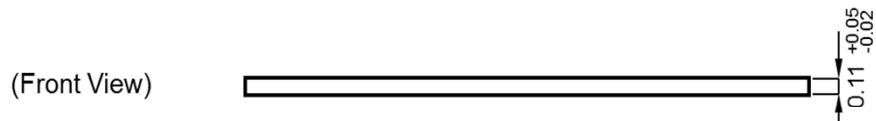
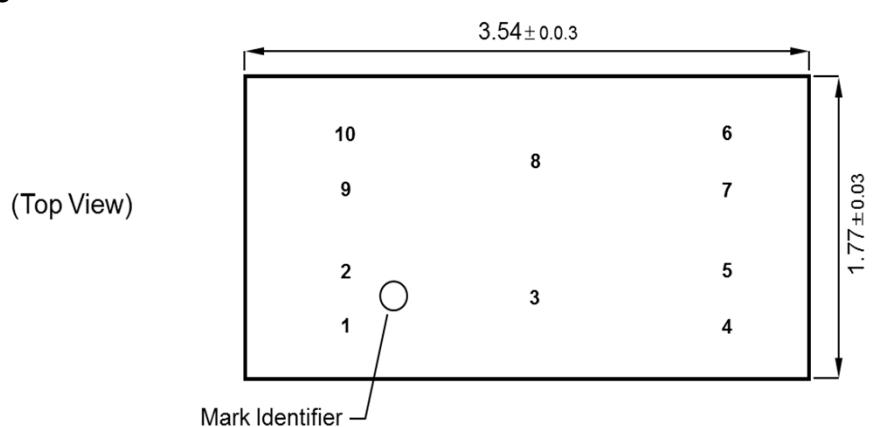
Dynamic Input/Output Characteristics

**Rth - tsw****Safe Operating Area****Thermal Response**

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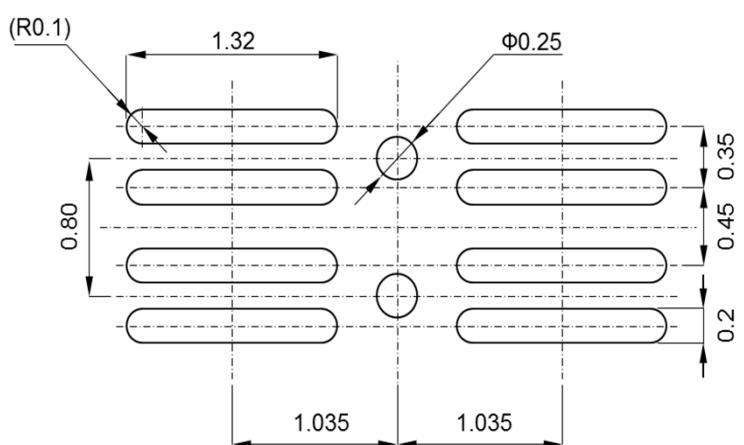
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■ Outline



■ Land Pattern (Reference)

Unit : mm



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